



# Product Change Notification

## 110389 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 110389 - 00  
**Change Title:** Intel® EP80578 Integrated Processors, 80578EG001C, 80578EG009C, and 80578EG800C, PCN 110389-00, Product Material, Documentation, Incoming Inspection Coplanarity Spec Change  
**Date of Publication:** January 06, 2011

## Key Characteristics of the Change:

Product Material

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Feb 23, 2011
<b>Date of First Availability of Post-Conversion Material:</b>	Feb 23, 2011

*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory or inclusion of post material conversion at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

Vermillion Range product built in the FCBGA7 package has a construction that, due to large form factor (37.5mmq) and big die size of 11.48mm x 11.176mm, sees a total coplanarity of up to 10.5 mils or 2.5 mils over the current Intel and JEDEC max of 8 mils at incoming inspection ambient room temperature. Intel is updating the outgoing coplanarity spec from 0mil ->8mil, to 5 mil -< 10.5mil at room temperature. The study has found that the change does not compromise the solder joint performance using the current recommended SMT process. This change is leveraging on previous Canmore product SMT data on upper spec limit and shadow moiré data on lower spec limit. Results of a detailed validation shows that doing this sees no increase in CTF ball integrity at the board level.

## Customer Impact of Change and Recommended Action:

Customers may start to get product that was inspected to the updated criteria of 10.5mils, however the inspection method does not change when doing an incoming inspection at ambient temperature. Customer will need to start accepting up to 10.5mils, and or start measuring the part at simulated SMT under heat conditions, (reference JEDEC Std SPP-024A) to confirm that coplanarity requirements are met. There is no change to your process. Intel anticipates there is no change to current SMT handling. Profiles, or quality impact to these products.

### Products Affected / Intel Ordering Codes:

Marketing Name	Frequency	Pre Conversion Product Code	Pre Conversion S-Spec	Pre Conversion MM#
Intel® EP80578 Integrated Processor, 805	800 MHz	LE80578EG800C S LH4J	S LH4J	905032
Intel® EP80578 Integrated Processor, 805	1.2 GHz	LE80578EG009C S LH6E	S LH6E	907864
Intel® EP80578 Integrated Processor, 805	1.0 GHz	LE80578EG001C S LH6F	S LH6F	907866

### PCN Revision History:

**Date of Revision:**

January 06, 2011

**Revision Number:**

00

**Reason:**

Originally Published PCN